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machining, each element including projecting portions, and fixing together said

projecting portions in assembling said enclosure.

42. (New) A method according to claim 41, wherein said machining

comprises machine-finishing of surfaces of the elements which constitute sealing

surfaces of the enclosure.

43. (New) A method of producing a conduction-cooled hardware

enclosure, comprising providing a plurality of enclosure pieces of a range of

differing sizes and usable in assembling enclosures of respective differing sizes,

selecting some of those pieces, assembling a thermally conductive enclosure of a

desired size and including the selected pieces and installing electronic hardware

in said enclosure in thermally conductive communication with said enclosure.

44. (New) A method according to claim 43, and further comprising

providing pieces of a standard size and each a triskelion form corner-piece, and

including the latter pieces in said enclosure during assembly of said enclosure.

REMARKS

It is respectfully requested that the Examiner consider the amended

claims enclosed herewith prior to examination.

Respectfully Submitted,

Arnold S. Weirkraub, Reg. No. 25523

PLUNKETT & COONEY, P.C.

38505 Woodward Avenue, Suite 3000

Bloomfield Hills, MI 48304

(248) 901-4000

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